Product / Process Change Notification

N° 2019-185-A

Dear Customer,

please find attached our INFINEON Technologies PCN:

Early PCN: Several changes affecting Gen 5P mosfets for D2PAK, DPAK, TO220 packages

Infineon Technologies AG
Postal Address Headquarters: Am Campeon 1-15, D-85579 Neubiberg, Phone +49 (0)89 234-0
Chairman of the Supervisory Board: Dr. Wolfgang Eder
Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Dr. Sven Schneider
Registered Office: Neubiberg
Commercial Register: München HRB 126492

Product / Process Change Notification

N° 2019-185-A

Products affected	Please refer to attached affected product list 1_cip19185_A

Detailed Change Information

Subject:	Early PCN: Several changes affecting Gen 5P mosfets for D2PAK, DPAK, TO220 packages	
Reason / Motivation:	Production Consolidation	
Description	**Old**	**New**
PROCESS - WAFER PRODUCTION: New / change of metallization (specifically chip backside)	Cr/Ni/Ag Sputter Process	Ti/Ni/Ag Evaporation Process
PROCESS - WAFER PRODUCTION: New / change of metallization (specifically chip frontside)	Al/Si	Al/Si/Cu
PROCESS - WAFER PRODUCTION: Move of all or part of wafer fab to a different location/site/subcontractor	Infineon Technologies Americas Corp., Temecula, United States	EPISIL Technologies Inc.
PROCESS - ASSEMBLY: Change in leadframe dimensions	Dpak part AUIRFR5410TRL only: Single gage leadframe	Dpak part AUIRFR5410TRL only: Dual gage leadframe
PROCESS - ASSEMBLY: Change of lead frame finishing material / area (internal)	TO220 and Dpak are affected only: Ni plated in all area Cu on die pad	TFME Only TO220 and Dpak: Bare Cu in all area
PROCESS - ASSEMBLY: Die attach material	Dpak parts 94-4103PBF, 94-4918PBFonly: Die Attach material 44-0014	Dpak parts 94-4103PBF, 94-4918PBF only: Die Attach material 44-0314
PROCESS - ASSEMBLY: Change of wire bonding	Dpak parts AUIRFR5305, AUIRFR5305TR, AUIRFR5305TRL only: 12 mil Al bond wire	Dpak parts , AUIRFR5305, AUIRFR5305TR, AUIRFR5305TRL only: 10 mil Al bond wire
PROCESS - ASSEMBLY: Change of mold compound / encapsulation material	TO220 only: MG15F-35A	TFME only TO220 only: KE-G300BH

Product / Process Change Notification

N° 2019-185-A

PROCESS - ASSEMBLY: Change of product marking	TO220 and Dpak: No Site code	TFME affected only: TO220 and Dpak; Site Code M
PROCESS - ASSEMBLY: Move of all or part of assembly to a different location/site/subcontractor.	TO220 and Dpak: Rectificadores Internacionales, S.A. de C.V., Tijuana , Mexico	TO220 and Dpak: Rectificadores Internacionales, S.A. de C.V., Tijuana , Mexico and Tongfu Microelectronics Co., Ltd(TFME)
TEST FLOW: Move of all or part of electrical wafer test and/or final test to a different location/site/subcontractor	Wafer Probe site: Infineon Technologies Americas Corp., Temecula, United States TO220 and Dpak: Final Test Rectificadores Internacionales, S.A. de	Wafer Probe site: EPISIL Technologies Inc. TO220 and Dpak: Final Test , Rectificadores Internacionales, S.A. de C.V., Tijuana , Mexico and Tongfu

Product Identification

Traceability assured via Lot number an date code.

Anticipated Impact of Change

No expected impact on electrical performance. Quality and reliability verified by qualification.

DeQuMa-ID(s): SEM-PW-06 / SEM-PW-07 / SEM-PW-13 / SEM-PA-03 / SEM-PA-04 / SEM-PA-07 / SEM-PA-08 / SEM-PA-11 / SEM-PA-13 / SEM-PA-18 / SEM-TF-01

Attachments

1_cip19185_A	affected product list
3_cip19185_A	customer information package

Time Schedule

Final qualification report	2021-02-28
First samples available	2021-02-28
Intended start of delivery [1]	2021-10-31
Last Order Date (LOD) [2]	2021-04-30
Last Delivery Date (LDD) [3]	2021-10-31

[1] provided date or earlier after customer approval
[2] Last time buy volume to be placed latest until LOD
[3] Delivery of new product can be earlier (see Intended start of delivery) and depends on approval

If you have any questions, please do not hesitate to contact your local Sales Office.